



LIGITEK

LIGITEK ELECTRONICS CO.,LTD.
Property of Ligitek Only

SINGLE DIGIT LED DISPLAY (0.36 Inch)



Lead-Free Parts

LSD315/64-XX/RP25-PF

DATA SHEET

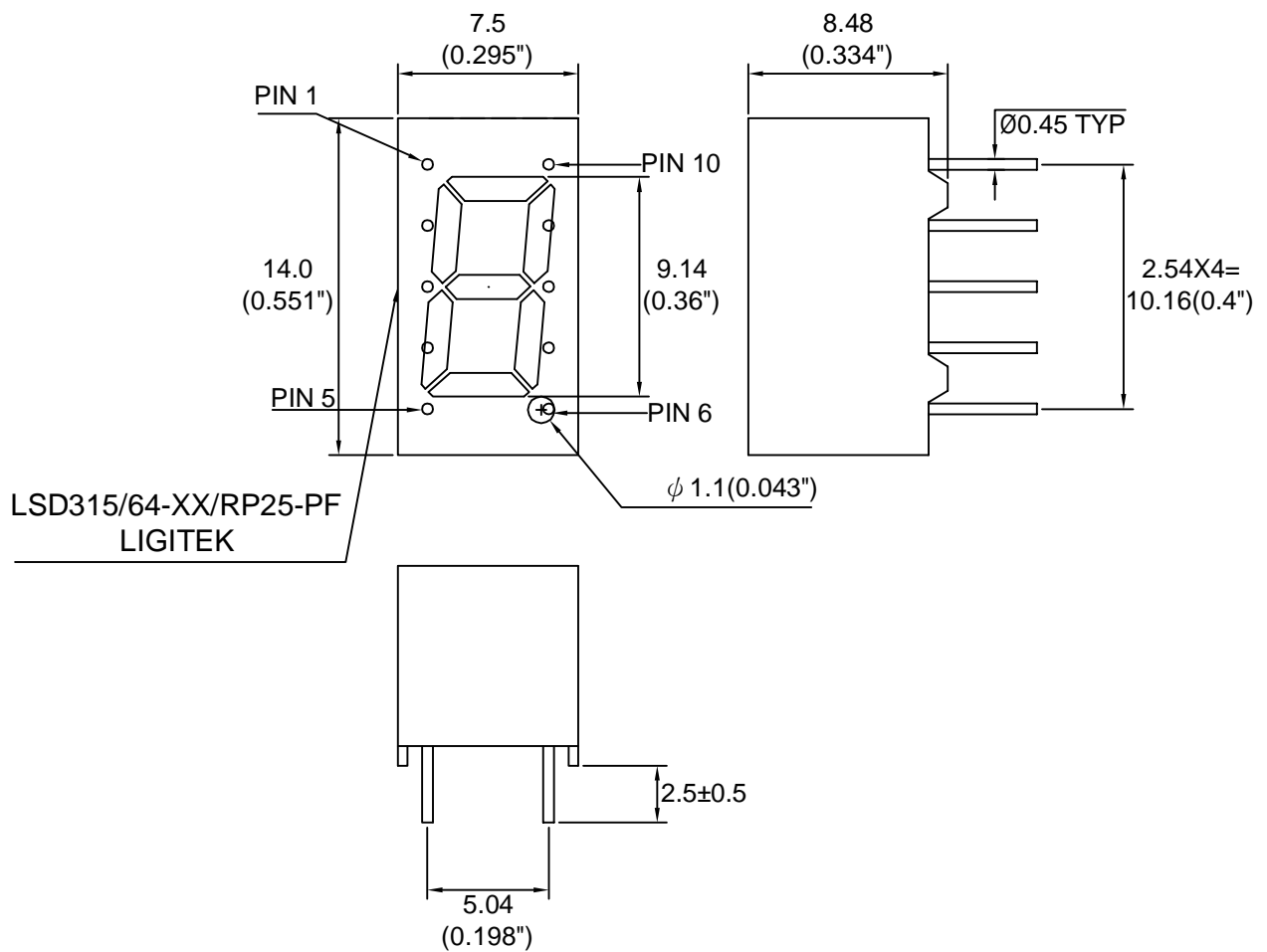
DOC. NO : QW0905-LSD315/64-XX/RP25-PF-08

REV. : A

DATE : 11 - Jan.- 2008



Package Dimensions



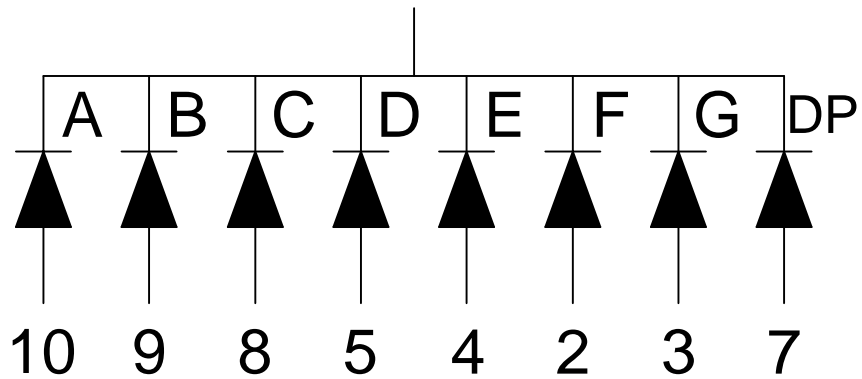
Note : 1.All dimension are in millimeters and (Inch) tolerance is ± 0.25 (0.01") unless otherwise noted.
2.Specifications are subject to change without notice.



Internal Circuit Diagram

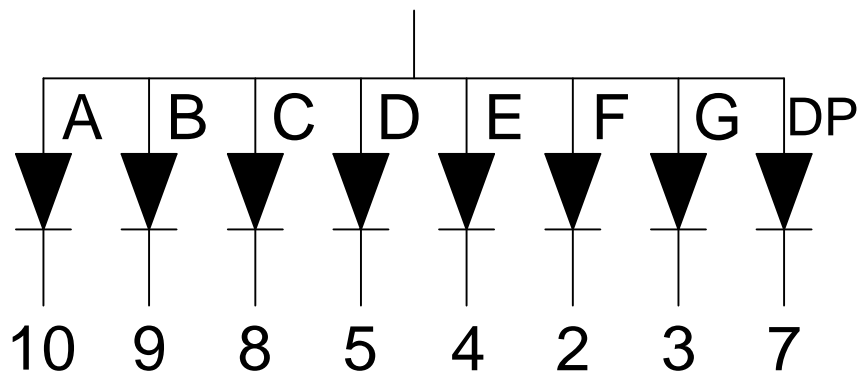
LSD3154-XX/RP25-PF

1,6



LSD3164-XX/RP25-PF

1,6





Electrical Connection

PIN NO.	LSD3154-XX/RP25-PF	PIN NO.	LSD3164-XX/RP25-PF
1	Common Cathode	1	Common Anode
2	Anode F	2	Cathode F
3	Anode G	3	Cathode G
4	Anode E	4	Cathode E
5	Anode D	5	Cathode D
6	Common Cathode	6	Common Anode
7	Anode DP	7	Cathode DP
8	Anode C	8	Cathode C
9	Anode B	9	Cathode B
10	Anode A	10	Cathode A



Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Ratings	UNIT
		Orange	
Forward Current Per Chip	IF	15	mA
Peak Forward Current Per Chip (Duty 1/10,0.1ms Pulse Width)	IFP	50	mA
Power Dissipation Per Chip	PD	50	mW
Reverse Current Per Any Chip	Ir	10	μA
Operating Temperature	Topr	-25 ~ +85	°C
Storage Temperature	Tstg	-25 ~ +85	°C

Part Selection And Application Information(Ratings at 25°C)

PART NO	CHIP		common cathode or anode	λ P (nm)	Δ λ (nm)	Electrical				IV-M
	Material	Emitted				Vf(v)		Iv(mcd)		
						Min.	Typ.	Min.	Typ.	
LSD3154-XX/RP25-PF	GaAsP/GaP	Orange	Common Cathode	635	45	1.7	2.1	0.8	1.75	2:1
LSD3164-XX/RP25-PF			Common Anode							

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.
2. The luminous intensity data did not including ±15% testing tolerance.



Test Condition For Each Parameter

Parameter	Symbol	Unit	Test Condition
Forward Voltage Per Chip	Vf	volt	If=10mA
Luminous Intensity Per Chip	Iv	mcd	If=10mA
Dominant Wavelength	λP	nm	If=20mA
Spectral Line Half-Width	$\Delta \lambda$	nm	If=20mA
Reverse Current Any Chip	Ir	μA	Vr=5V
Luminous Intensity Matching Ratio	IV-M		



Typical Electro-Optical Characteristics Curve

E CHIP

Fig.1 Forward current vs. Forward Voltage

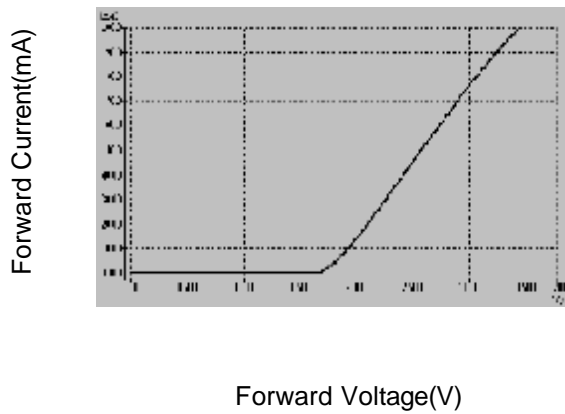


Fig.2 Relative Intensity vs. Forward Current

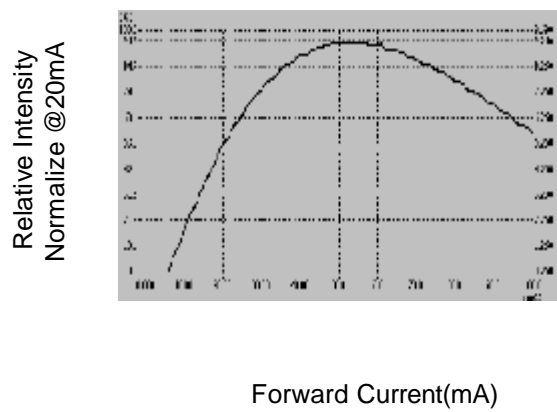


Fig.3 Forward Voltage vs. Temperature

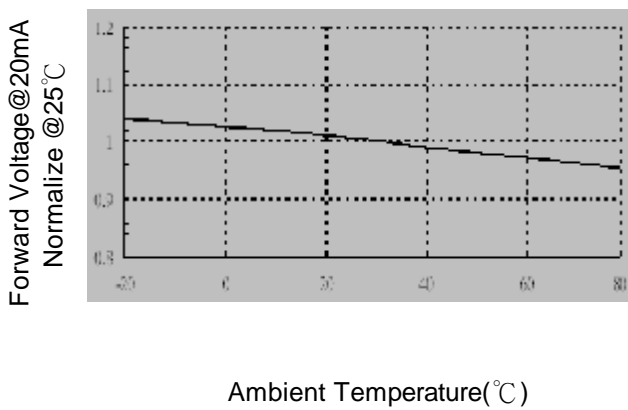


Fig.4 Relative Intensity vs. Temperature

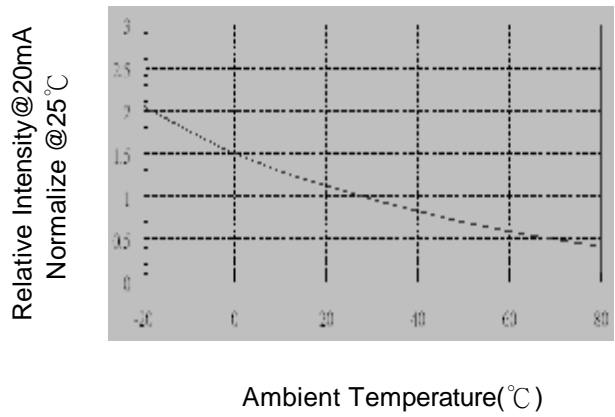
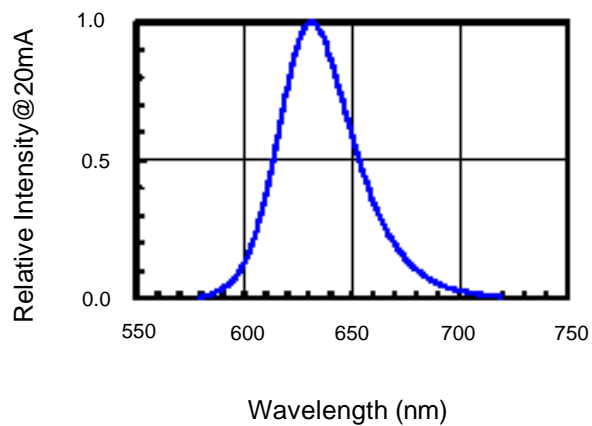


Fig.5 Relative Intensity vs. Wavelength





Soldering Condition(Pb-Free)

1.Iron:

Soldering Iron:30W Max

Temperature 350 °C Max

Soldering Time:3 Seconds Max(One time only)

Distance:Solder Temperature 1/16 Inch Below Seating
Plane For 3 Seconds At 260 °C

2.Wave Soldering Profile

Dip Soldering

Preheat: 120° C Max

Preheat time: 60seconds Max

Ramp-up

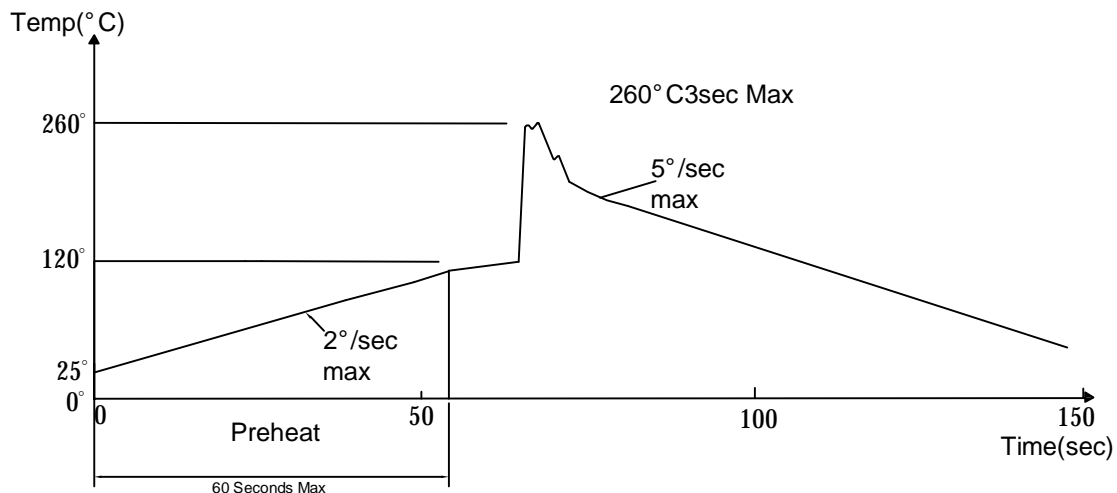
2° C/sec(max)

Ramp-Down:-5° C/sec(max)

Solder Bath:260° C Max

Dipping Time:3 seconds Max

Distance:Solder Temperature 1/16 Inch Below Seating
Plane For 3 Seconds At 260° C



Note: 1.Wave solder should not be made more than one time.
2.You can just only select one of the soldering conditions as above.



Reliability Test:

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=10mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of detemining the resistance of a part in electrical and themal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 °C±5°C 2.RH=90 %-95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 °C±5°C & -40 °C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 °C±5°C 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 °C±5°C 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2